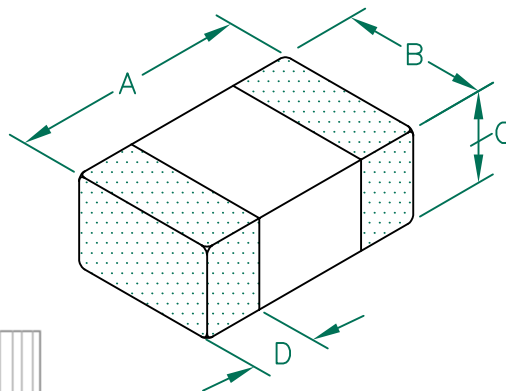


CPI1008J3R3R-10

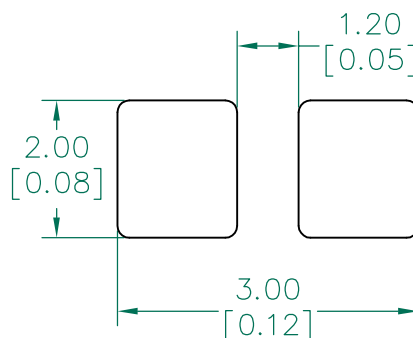
**UNCONTROLLED
DOCUMENT**

PHYSICAL DIMENSIONS:

A	2.50 [.098]	+ 0.20[.008]
B	2.00 [.079]	+ 0.20[.008]
C	0.90 [.035]	+ 0.10[.004]
D	0.60 [.024]	+ 0.20[.008]



LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.763 [0.030] to this dimension)

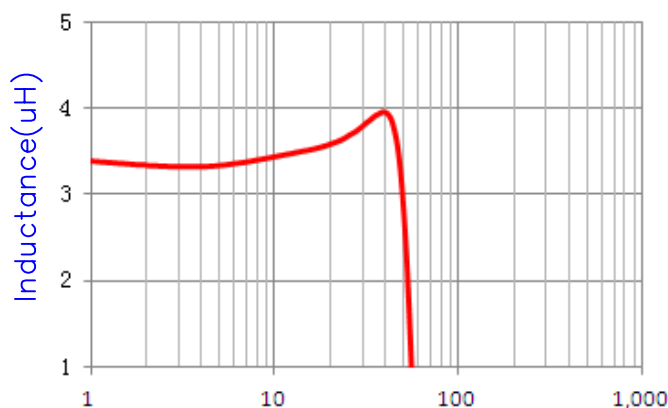
ELECTRICAL CHARACTERISTICS:

	L (μ H) @ 1MHz $\pm 20\%$	DCR (Ω) $\pm 25\%$	I (Max)
Nom	3.30	0.1600	
Min	2.64	0.1200	
Max	3.96	0.2000	1200mA

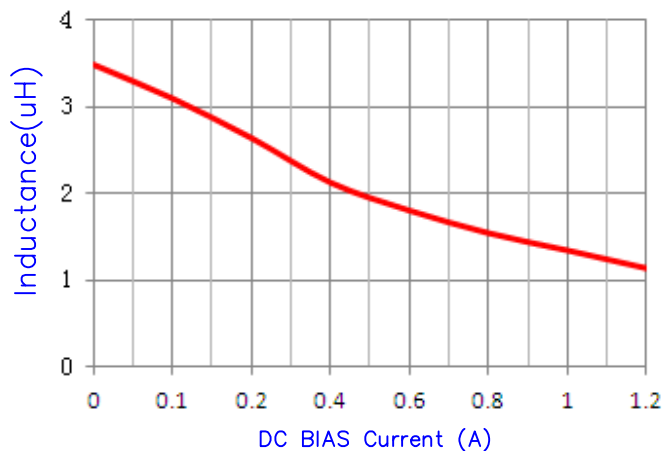
NOTES: UNLESS OTHERWISE SPECIFIED

1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL, EMBOSSED PLASTIC TAPE.
2. TERMINATION FINISH IS 100% MATTE Sn OVER Ni.
3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
4. I (MAX.) IS BASED ON THE MAXIMUM SUSTAINED CURRENT APPLIED WHILE MAINTAINING A MAXIMUM TEMPERATURE RISE OF 40°C OVER AMBIENT.
5. OPERATION TEMPERATURE TEMP: -55°C~+125°C (INCLUDING SELF-HEATING)

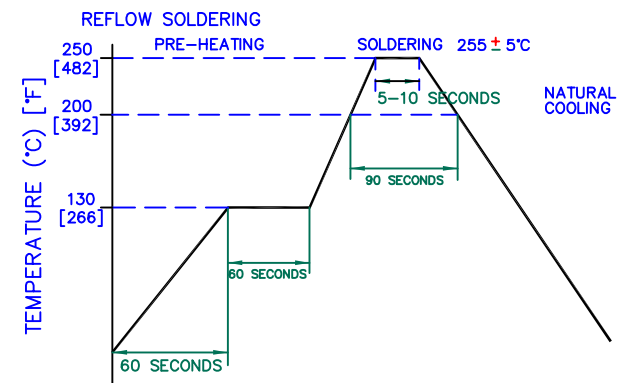
Ls vs Frequency



Ls vs DC BIAS Current



RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES]				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.			
C	UPDATE PAD DIMENSION ROHS	07/08/14	QU	PROJECT/PART NUMBER: CPI1008J3R3R-10			
B	UPDATE LAIRD LOGO AND NOTES 5	08/05/13	QU	DATE: 03/01/11			
A	ORIGINAL DRAFT	03/01/11	QU	SCALE: NTS			
REV	DESCRIPTION	DATE	INT	SHEET: 1 of 1			